

IN THE CLAIMS

Please amend the claims as shown in the marked up copy to read as follows:

B<sub>1</sub> 4. (Amended) An aqueous dispersion for chemical mechanical polishing defined in Claim 3, wherein said organic compound is at least one from among (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) guanine, (6) salicylaldoxime, (7) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (8) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (9) a heterocyclic compound with a heteropentacycle and with no benzene ring forming the skeleton and with a functional group, (10) a heterocyclic compound with a heteropentacycle and with a benzene ring forming the skeleton, (11) a heterocyclic compound with a heterohexacycle bearing two or more hetero atoms and with either or both a functional group and/or a benzene ring forming the skeleton, and a derivative of any of compounds (1) through (11).

B<sub>2</sub> 12. (Amended) An aqueous dispersion for chemical mechanical polishing defined in any one of Claim 11, wherein said organic compound is at least one from among (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldoxime, (8) copperon, (9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (12) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic compound with a heteropentacycle and with no benzene ring forming the skeleton and with a functional group, (14) a heterocyclic compound with a heteropentacycle and with a benzene ring forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms, and a derivative of any of compounds (1)

B<sub>2</sub> Cont through (15).

17. (Amended) An aqueous dispersion for chemical mechanical polishing defined in Claim 16, wherein said organic compound is at least one from among (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldoxime, (8) copperon, (9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (12) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic compound with a heteropentacycle and with no benzene ring forming the skeleton and with a functional group, (14) a heterocyclic compound with a heteropentacycle and with a benzene ring forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms, and a derivative of any of compounds (1) through (15).

B<sub>4</sub> 22. (Amended) An aqueous dispersion for chemical mechanical polishing defined in Claim 21, wherein said organic compound is at least one from among (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldoxime, (8) copperon, (9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (12) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic compound with a heteropentacycle and with no benzene ring forming the skeleton and with a functional group, (14) a heterocyclic compound with a heteropentacycle and with a benzene ring forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms, and a derivative of any of compounds (1) through (15).

B<sub>5</sub> 27. (Amended) An aqueous dispersion for chemical mechanical polishing defined in Claim 26, wherein said organic compound is at least one from among (1) biphenol, (2)

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bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldoxime, (8) copperon, (9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (12) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic compound with a heteropentacycle and with no benzene ring forming the skeleton and with a functional group, (14) a heterocyclic compound with a heteropentacycle and with a benzene ring forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms, and a derivative of any of compounds (1) through (15).

33. (Amended) A method of inhibiting generation of pits on a polishing surface of an object in need thereof, comprising:

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mixing an aqueous dispersion comprising water, an abrasive, and one or more organic compounds selected from the group consisting of (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) guanine, (6) salicylaldoxime, (7) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (8) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (9) a heterocyclic compound with a heteropentacycle and without a benzene ring forming the skeleton and with a functional group, (10) a heterocyclic compound with a heteropentacycle and with a benzene ring forming the skeleton, (11) a heterocyclic compound with a heterohexacycle bearing two or more hetero atoms and with either or both a functional group and/or a benzene ring forming the skeleton, and (12) a derivative of any of compounds (1) through (11);

supplying said aqueous dispersion to the surface of a polishing pad; and

chemical mechanical polishing a polishing surface of an object in need thereof in the

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Ent presence of said aqueous dispersion.

39. (Amended) A method of suppressing reduction of performance of a polishing pad of an object in need thereof and inhibiting generation of pits on a polishing surface of an object in need thereof, comprising:

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mixing an aqueous dispersion comprising water, an abrasive, and one or more organic compounds selected from the group consisting of (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldoxime, (8) copperon, (9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (12) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic compound with a heteropentacycle, without a benzene ring forming the skeleton and with a functional group, (14) a heterocyclic compound with a heteropentacycle, with a benzene ring forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms, and (16) a derivative of any of compounds (1) through (15);

supplying said aqueous dispersion to the surface of a polishing pad; and

chemical mechanical polishing a polishing surface of an object in need thereof in the presence of said aqueous dispersion.

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43. (Amended) A method of suppressing reduction of performance of a polishing pad of an object in need thereof and flattening uneven sections on a polishing surface of an object in need thereof, comprising:

mixing an aqueous dispersion comprising water, an abrasive, and one or more organic compounds selected from the group consisting of (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldoxime, (8) copperon,

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(9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (12) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic compound with a heteropentacycle, without a benzene ring forming the skeleton and with a functional group, (14) a heterocyclic compound with a heteropentacycle, with a benzene ring forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms, and (16) a derivative of any of compounds (1) through (15);

supplying said aqueous dispersion to the surface of a polishing pad; and  
chemical mechanical polishing a polishing surface of an object in need thereof in the presence of said aqueous dispersion.

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47. (Amended) A method of inhibiting generation of pits on a polishing surface of an object in need thereof and flattening uneven sections on a polishing surface of an object in need thereof, comprising:

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mixing an aqueous dispersion comprising water, an abrasive, and one or more organic compounds selected from the group consisting of (1) biphenol, (2) bipyridyl, (3) vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldoxime, (8) copperon, (9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to an alkylene group, (12) a compound with a total of two or more amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic compound with a heteropentacycle, without a benzene ring forming the skeleton and with a functional group, (14) a heterocyclic compound with a heteropentacycle, with a benzene ring forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms, and (16) a derivative of any of compounds (1) through (15);

B9 supplying said aqueous dispersion to the surface of a polishing pad; and  
chemical mechanical polishing a polishing surface of an object in need thereof in the  
presence of said aqueous dispersion.

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51. (Amended) A method of suppressing reduction of performance of a polishing pad  
of an object in need thereof, inhibiting generation of pits on a polishing surface of an object in  
need thereof, and flattening uneven sections on a polishing surface of an object in need  
thereof, comprising:

B10 mixing an aqueous dispersion comprising water, an abrasive, and one or more organic  
compounds selected from the group consisting of (1) biphenol, (2) bipyridyl, (3)  
vinylpyridine, (4) hypoxanthine, (5) adenine, (6) guanine, (7) salicylaldoxime, (8) copperon,  
(9) cysteine, (10) thiourea, (11) a compound with a total of two or more amino groups and/or  
hydroxyl groups bonded to an alkylene group, (12) a compound with a total of two or more  
amino groups and/or hydroxyl groups bonded to a benzene ring, (13) a heterocyclic  
compound with a heteropentacycle, without a benzene ring forming the skeleton and with a  
functional group, (14) a heterocyclic compound with a heteropentacycle, with a benzene ring  
forming the skeleton, (15) a heterohexacyclic compound bearing two or more hetero atoms,  
and (16) a derivative of any of compounds (1) through (15);

supplying said aqueous dispersion to the surface of a polishing pad; and  
chemical mechanical polishing a polishing surface of an object in need thereof in the  
presence of said aqueous dispersion.

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